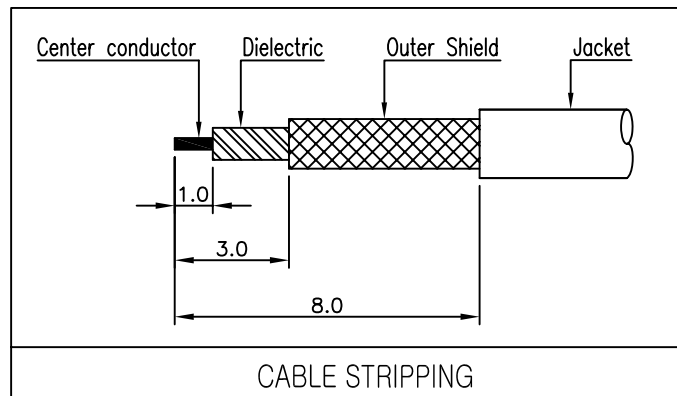
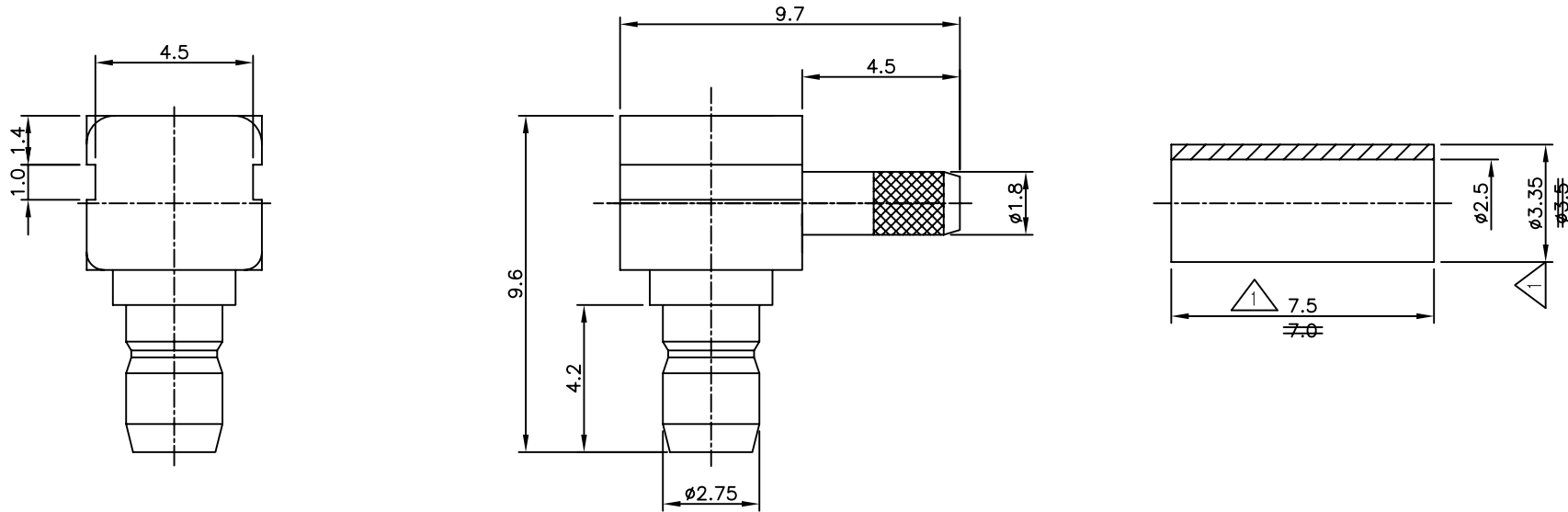


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	E.H.KIM	I.C.KIM	2013.06.04.
1	[설번No.202201-0009] PIPE 압착 후 BURR 발생 개선으로 인한 PIPE 변경	S.Y.EUN	S.H.KIM	2022.01.18.



5	COVER	1	MBsBD	Gold Plate	DCO00013-5/1
4	INSULATOR	1	MBsBD	Gold Plate	DIN02166-N/1
3	FERRULE	1	MBsBD	Nickel Plate Gold Plate	DFE00018-5/3 DFE00009-5/1
2	CONTACT	1	BeCu	Gold Plate	DCT02818-5/1
1	1-2 BODY (B)	1	MBsBD	Gold Plate	DBD03343-3/1
	1-1 BODY (A)	1	MBsBD		DBD00350-5/1 DBD00035-3/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2022. 01. 18.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	S.H.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SSMB50 trans(Ø2.75) CABLE JL RG178
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	5/1	A4 DWG NO. CN02978-7/3 REVISION 1 SHEET 1 of 1
		UNIT	mm	